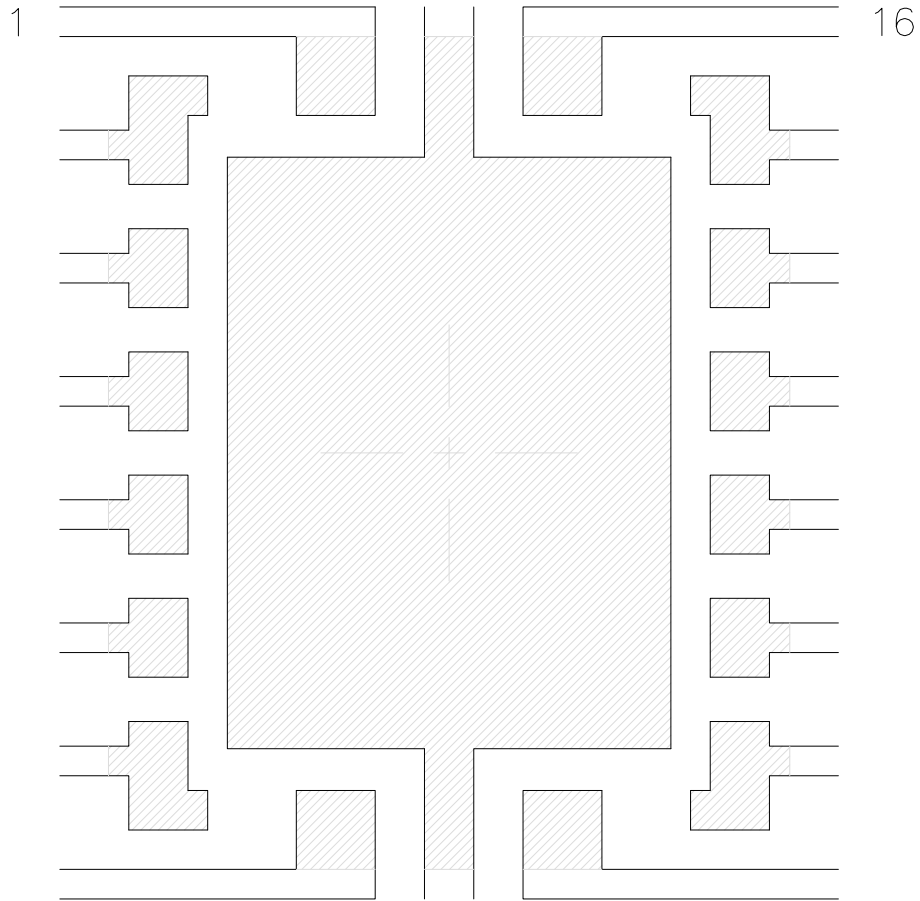



REVISIONS		
REV	DESCRIPTION	DATE
B	DRAWING UPDATE	09-19-16



 Ag PLATING

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CUSTOMER: xxxxx	REF. DWG #: QSSOP16-A03 REV. 0	 www.promex-ind.com	
PROJECT NAME: xxxxx	L/F PN: 235-10018 (SSOP16-01-A10)		
DIE SIZE: xxxxx	DAP SIZE: 0.090" X 0.120"	TITLE QSOP 16L 0.150" WIDE BODY BOND SHELL	
DIE THICKNES, um: xxxxx	DAP PLATING OPTION: SPOT		
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: Ag 150 u"	DWG NO.	REV
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 HH	16L-QSOP-150W-635P-BD.DWG	B
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.008" ±0.0003"	DO NOT SCALE	FILE NAME
			16L-QSOP-150W-635P-BD.DWG
			SHEET
			1 OF 1